



N-Channel 200-V (D-S) MOSFET

PRODUCT SUMMARY		
V _{DS} (V)	r _{DS(on)} (Ω)	I _D (A)
200	0.080 @ V _{GS} = 10 V	5.3
	0.090 @ V _{GS} = 6 V	5.0

FEATURES

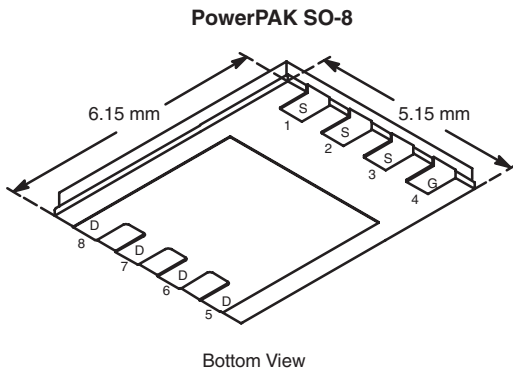
- TrenchFET[®] Power MOSFETS
- New Low Thermal Resistance PowerPAK[®] Package with Low 1.07-mm Profile
- PWM Optimized for Fast Switching
- 100 % R_g Tested



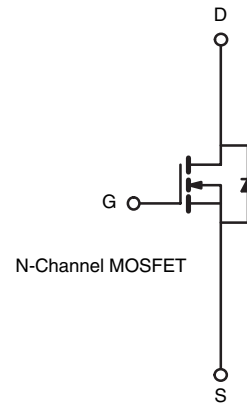
RoHS*
COMPLIANT

APPLICATIONS

- Primary Side Switch for High Density DC/DC
- Telecom/Server 48-V DC/DC
- Industrial and 42-V Automotive



Ordering Information: Si7450DP-T1
Si7450DP-T1—E3 (Lead (Pb)-Free)



ABSOLUTE MAXIMUM RATINGS T _A = 25 °C, unless otherwise noted					
Parameter	Symbol	10 secs	Steady State	Unit	
Drain-Source Voltage	V _{DS}	200		V	
Gate-Source Voltage	V _{GS}	±20			
Continuous Drain Current (T _J = 150°C) ^a	I _D	T _A = 25°C	5.3	3.2	A
		T _A = 70°C	4.3	2.6	
Pulsed Drain Current	I _{DM}	40			
Avalanche Current	I _{AS}	15			
Continuous Source Current (Diode Conduction) ^a	I _S	4.3	1.6	W	
Maximum Power Dissipation ^a	P _D	T _A = 25°C	5.2		1.9
		T _A = 70°C	3.3		1.2
Operating Junction and Storage Temperature Range	T _J , T _{stg}	-55 to 150		°C	
Soldering Recommendations (Peak Temperature) ^{b,c}		260			

THERMAL RESISTANCE RATINGS					
Parameter		Symbol	Typical	Maximum	Unit
Maximum Junction-to-Ambient ^a	t ≤ 10 sec	R _{thJA}	19	24	°C/W
	Steady State		52	65	
Maximum Junction-to-Case (Drain)	Steady State	R _{thJC}	1.5	1.8	

Notes

a. Surface Mounted on 1" x 1" FR4 Board.

b. See Solder Profile (<http://www.vishay.com/ppg?73257>). The PowerPAK SO-8 is a leadless package. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection.

c. Rework Conditions: manual soldering with a soldering iron is not recommended for leadless components.

* Pb containing terminations are not RoHS compliant, exemptions may apply.



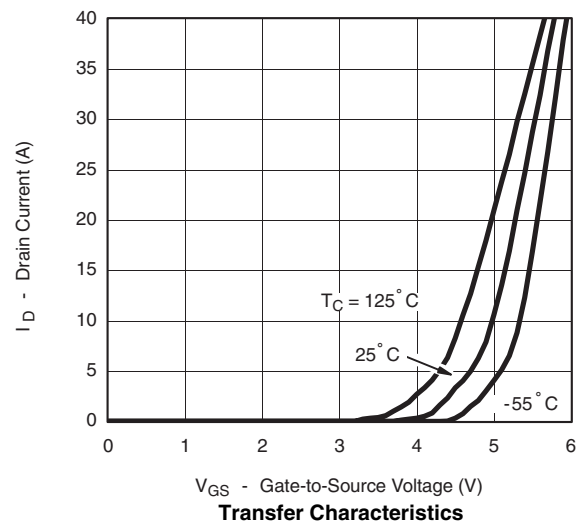
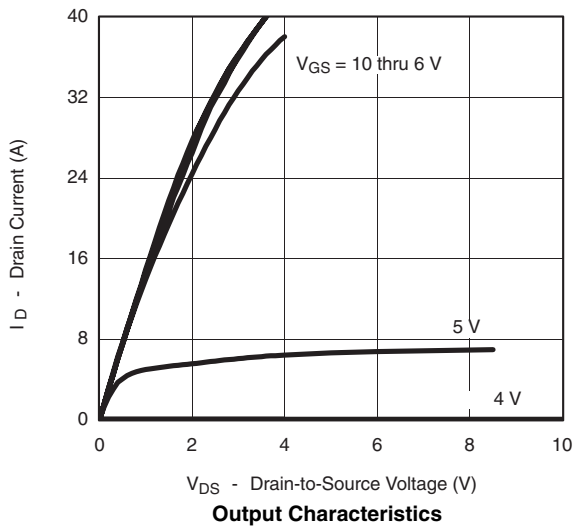
SPECIFICATIONS $T_J = 25\text{ }^\circ\text{C}$, unless otherwise noted						
Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Static						
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\text{ }\mu\text{A}$	2.0		4.5	V
Gate-Body Leakage	I_{GSS}	$V_{DS} = 0\text{ V}, V_{GS} = \pm 20\text{ V}$			± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 200\text{ V}, V_{GS} = 0\text{ V}$			1	μA
		$V_{DS} = 200\text{ V}, V_{GS} = 0\text{ V}, T_J = 55\text{ }^\circ\text{C}$			5	
On-State Drain Current ^a	$I_{D(on)}$	$V_{DS} \geq 5\text{ V}, V_{GS} = 10\text{ V}$	40			A
Drain-Source On-State Resistance ^a	$r_{DS(on)}$	$V_{GS} = 10\text{ V}, I_D = 4.0\text{ A}$		0.065	0.080	Ω
		$V_{GS} = 6.0\text{ V}, I_D = 4.0\text{ A}$		0.070	0.090	
Forward Transconductance ^a	g_{fs}	$V_{DS} = 15\text{ V}, I_D = 5\text{ A}$		19		S
Diode Forward Voltage ^a	V_{SD}	$I_S = 2.8\text{ A}, V_{GS} = 0\text{ V}$		0.75	1.2	V
Dynamic^b						
Total Gate Charge	Q_g	$V_{DS} = 100\text{ V}, V_{GS} = 10\text{ V}, I_D = 4.0\text{ A}$		34	42	nC
Gate-Source Charge	Q_{gs}			7.5		
Gate-Drain Charge	Q_{gd}			12.0		
Gate Resistance	R_g		0.2	0.85	1.5	Ω
Turn-On Delay Time	$t_{d(on)}$	$V_{DD} = 100\text{ V}, R_L = 25\text{ }\Omega$ $I_D \cong 4.0\text{ A}, V_{GEN} = 10\text{ V}, R_G = 6\text{ }\Omega$		14	20	ns
Rise Time	t_r			20	30	
Turn-Off Delay Time	$t_{d(off)}$			32	50	
Fall Time	t_f			25	35	
Source-Drain Reverse Recovery Time	t_{rr}	$I_F = 2.8\text{ A}, di/dt = 100\text{ A}/\mu\text{s}$		70	100	

Notes

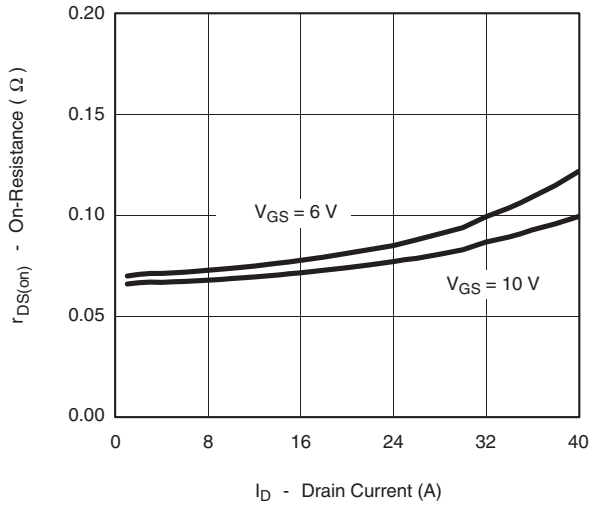
- a. Pulse test; pulse width $\leq 300\text{ }\mu\text{s}$, duty cycle $\leq 2\%$.
- b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

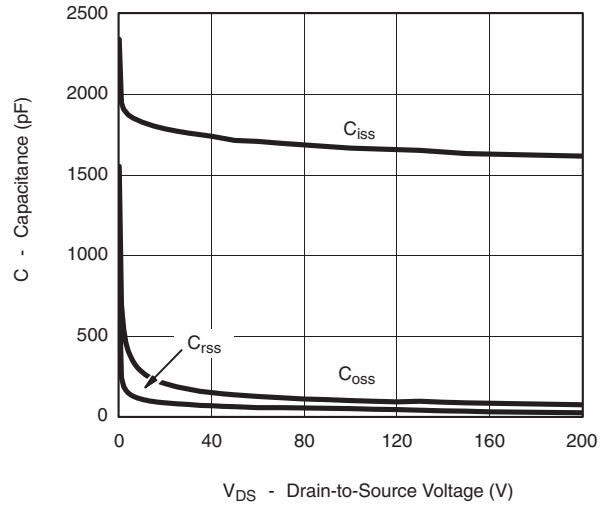
TYPICAL CHARACTERISTICS $25\text{ }^\circ\text{C}$, unless noted



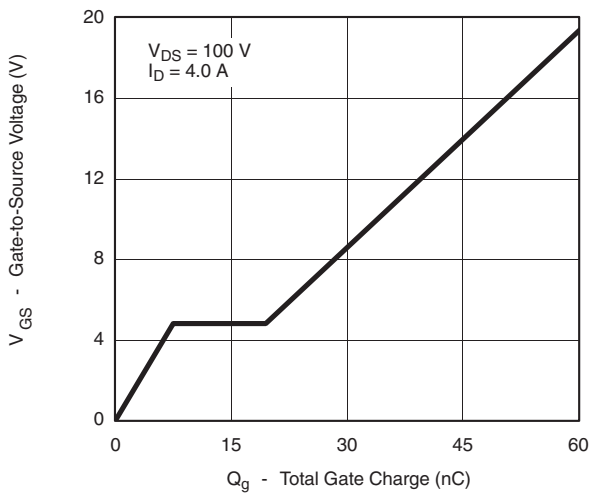
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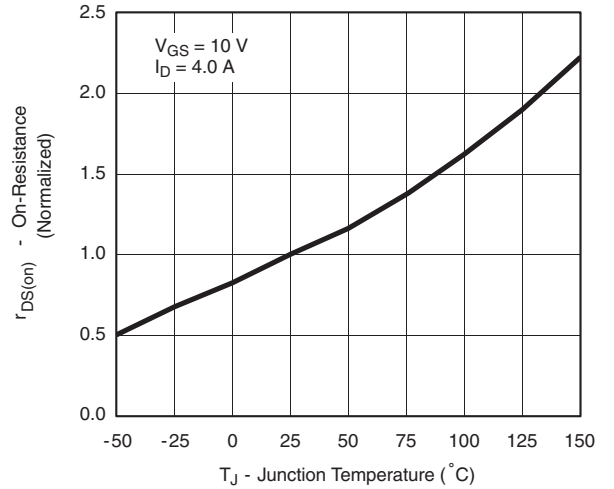
On-Resistance vs. Drain Current



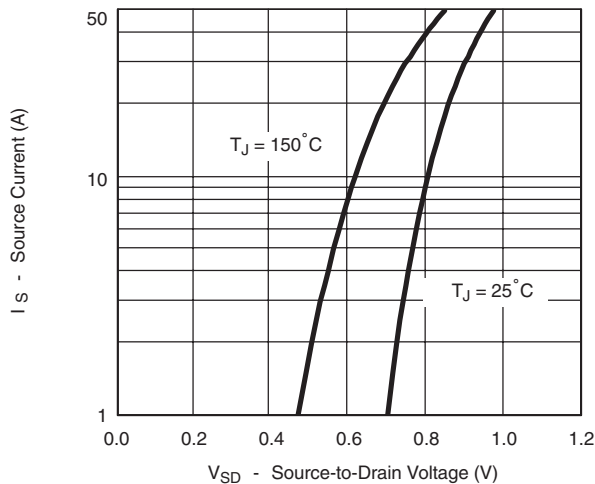
Capacitance



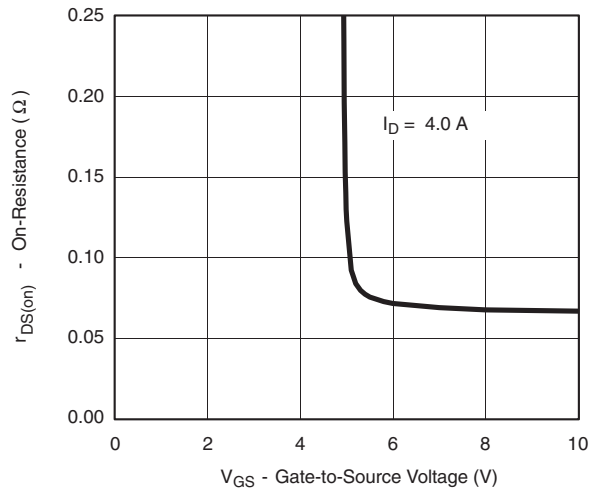
Gate Charge



On-Resistance vs. Junction Temperature

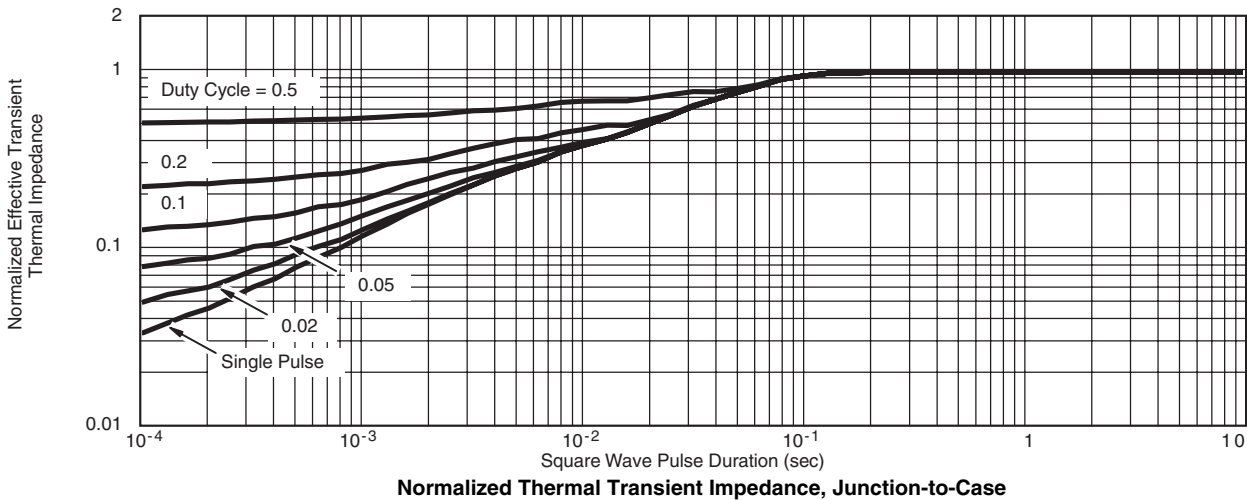
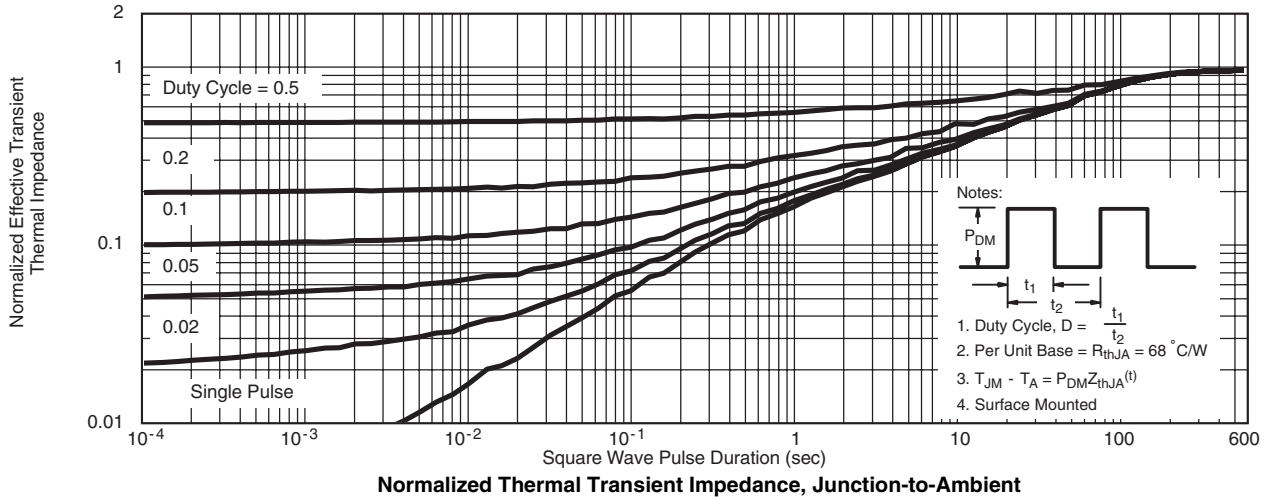
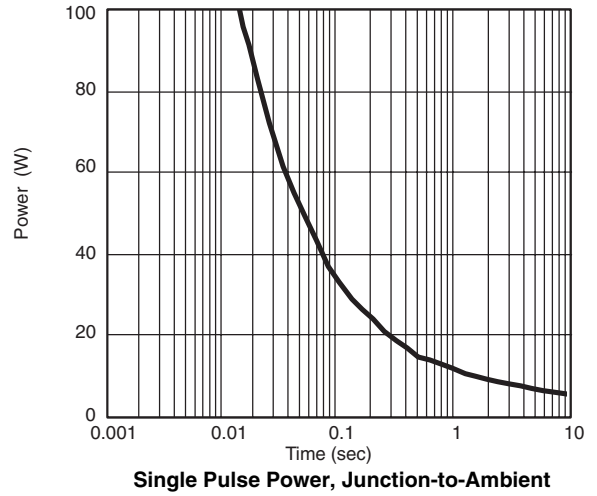
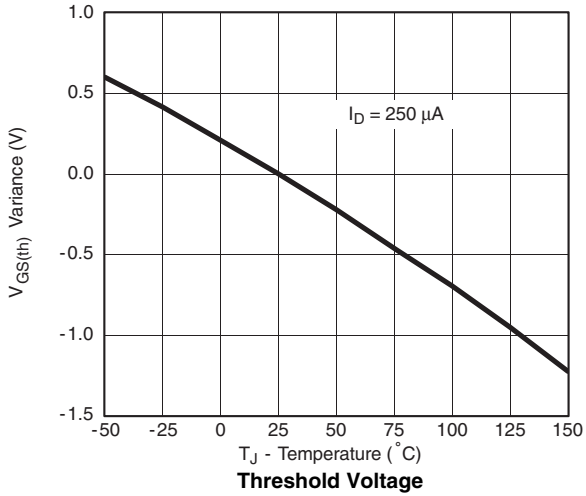


Source-Drain Diode Forward Voltage



On-Resistance vs. Gate-to-Source Voltage

TYPICAL CHARACTERISTICS 25 °C, unless noted



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